



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
<i>* : Required Field</i>			

<b>Supplier Information</b>			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2018-04-17</b>
<b>Contact Name *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Authorized Representative *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Rossana Bonaccorso</b>	<b>Representative Title</b>	<b>ADG MD Champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD60NF06T4	XMDP*ED6FB6F	A	998G	2018-04-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	330	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
SIP	6.5-6.1-2.3	3	GULL WING
Comment	TO 252 DPAK		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.16	Die - Leadframe	3503
Lead	6.22	Soft solder	18858

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	XMDP*ED6FB6F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	7.393	mg	supplier	die	Silicon (Si)	7440-21-3		7.152	mg	967402	21673
				supplier	metallization	Aluminium (Al)	7429-90-5		0.139	mg	18802	421
				supplier	Passivation	Silicon Oxide	7631-86-9		0.039	mg	5275	118
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	540	12
				supplier	back side metallization	Gold (Au)	7440-57-5		0.010	mg	1353	30
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.049	mg	6628	148
Leadframe	M-004 Copper and its alloys	166.052	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.730	mg	992039	499182
				supplier	alloy	iron (Fe)	7439-89-6		0.165	mg	994	500
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.050	mg	300	152
				supplier	metallization	Nickel (Ni)	7440-02-0		1.107	mg	6667	3355
Soft solder	Solder	6.727	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	6.223	mg	925078	18858
				supplier	solder	Tin (Sn)	7440-31-5		0.336	mg	49948	1018
				supplier	solder	Silver (Ag)	7440-22-4		0.168	mg	24974	509
Bonding wires	M-011 Other inorganic materials	0.923	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.923	mg	1000000	2797
Encapsulation	M-011 Other inorganic materials	147.860	mg	supplier	mold compound	Silica, vitreous	60676-86-0		129.378	mg	875003	392055
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-bi	EC 413-900-7		5.914	mg	39997	17921
				supplier	mold compound	Epoxy Resin	25068-38-6		4.436	mg	30001	13442
				supplier	mold compound	phenol resin	29690-82-2		7.393	mg	50000	22403
				supplier	mold compound	Carbon black	1333-86-4		0.739	mg	4999	2239
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167